

| L Number | Hits  | Search Text  | DB                       | Time stamp       |
|----------|-------|--|--------------------------|------------------|
| 1        | 3     | (yi-sang-hyun kim-yööng-nam).in.   | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:01 |
| 2        | 75    | multilayer with metalization   | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:02 |
| 3        | 54    | multi-layer with metalization  | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:02 |
| 4        | 204   | multiple with metalization   | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:06 |
| 5        | 321   | (multilayer with metalization) (multi-layer with metalization) (multiple with metalization)              | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:02 |
| 6        | 15    | ((multilayer with metalization) (multi-layer with metalization) (multiple with metalization)) and crack? | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:02 |
| 7        | 14267 | thermal adj stress   | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:06 |
| 8        | 2659  | crack? and (thermal adj stress)  | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:04 |
| 12       | 3154  | (257/750,758;438/622).CCLS.  | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:06 |
| 13       | 3     | multiple with metalization   | EPO; JPO; DERWENT        | 2003/05/02 15:06 |
| 14       | 13917 | thermal adj stress   | EPO; JPO; DERWENT        | 2003/05/02 15:06 |
| 15       | 766   | (thermal adj stress) and crack?  | EPO; JPO; DERWENT        | 2003/05/02 15:06 |
| 16       | 187   | ((thermal adj stress) and crack?) and semiconductor  | EPO; JPO; DERWENT        | 2003/05/02 15:08 |
| 10       | 225   | (crack? and (thermal adj stress)) and 438/\$.ccls.   | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:15 |
| 17       | 162   | ((crack? and (thermal adj stress)) and 438/\$.ccls.) and @ad<20010220                                    | USPAT; US-PGPUB; IBM_TDB | 2003/05/02 15:15 |